

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Molding shrinkage, parallel	0.4 / *	%	ISO 294-4, 2577
<sup>[C]</sup> Molding shrinkage, normal	0.9 / *	%	ISO 294-4, 2577

[C]: CAMPUS

Mechanical properties	dry / cond	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Tensile Modulus	9500 / 6000	MPa	ISO 527
<sup>[C]</sup> Stress at break	180 / 110	MPa	ISO 527
<sup>[C]</sup> Strain at break	3.5 / 6	%	ISO 527
Flexural modulus, 23°C	8500 / 500	MPa	ISO 178
Flexural strength	270 / 160	MPa	ISO 178
<sup>[C]</sup> Charpy impact strength, +23°C	90 / 105	kJ/m <sup>2</sup>	ISO 179/1eU
<sup>[C]</sup> Charpy impact strength, -30°C	75 / 90	kJ/m <sup>2</sup>	ISO 179/1eU
<sup>[C]</sup> Charpy notched impact strength, +23°C	15 / 25	kJ/m <sup>2</sup>	ISO 179/1eA
<sup>[C]</sup> Charpy notched impact strength, -30°C	9 / 22	kJ/m <sup>2</sup>	ISO 179/1eA

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Melting temperature, 10°C/min	221 / *	°C	ISO 11357-1/-3
<sup>[C]</sup> Temp. of deflection under load, 1.80 MPa	215 / *	°C	ISO 75-1/-2
<sup>[C]</sup> Temp. of deflection under load, 0.45 MPa	220 / *	°C	ISO 75-1/-2
<sup>[C]</sup> Burning Behav. at thickness h	HB / *	class	IEC 60695-11-10
Thickness tested	0.8 / *	mm	-

[C]: CAMPUS

Electrical properties	dry / cond	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Volume resistivity	1E13 / -	Ohm*m	IEC 62631-3-1
<sup>[C]</sup> Surface resistivity	* / 1E13	Ohm	IEC 62631-3-2
<sup>[C]</sup> Comparative tracking index	500 / -	-	IEC 60112

[C]: CAMPUS

Other properties	dry / cond	Unit	Test Standard
<sup>[C]</sup> Density	1360 / -	kg/m <sup>3</sup>	ISO 1183

[C]: CAMPUS

## Characteristics

### Processing

Injection Molding